Haegyu Jang

List of Publications by Year in descending order

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| # | Article | IF | CITATIONS |
|---|---|-----|-----------|
| 1 | Sensitivity Enhancement of SiO ₂ Plasma Etching Endpoint Detection Using Modified Gaussian Mixture Model. IEEE Transactions on Semiconductor Manufacturing, 2020, 33, 252-257. | 1.7 | 10 |
| 2 | Sensitivity Enhancement of Dielectric Plasma Etching Endpoint Detection by Optical Emission Spectra With Modified \$K\$ -Means Cluster Analysis. IEEE Transactions on Semiconductor Manufacturing, 2017, 30, 17-22. | 1.7 | 13 |
| 3 | Effect of Dual Radio Frequency Bias Power on SiO ₂ Sputter Etching in Inductively Coupled Plasma. Nano, 2017, 12, 1750025. | 1.0 | 3 |
| 4 | Characterization of Low-k SiCOH Film Etching in Fluorocarbon Inductively Coupled Plasmas. Nanoscience and Nanotechnology Letters, 2017, 9, 174-178. | 0.4 | 2 |
| 5 | Patterning of Si3N4 Layer in Pulse-Biased Capacitively-Coupled Plasmas for Multi-Level Hard Mask Structures. Journal of Nanoscience and Nanotechnology, 2016, 16, 11817-11822. | 0.9 | 1 |
| 6 | Characterization of Low Temperature Graphene Synthesis in Inductively Coupled Plasma Chemical Vapor Deposition Process with Optical Emission Spectroscopy. Journal of Nanoscience and Nanotechnology, 2014, 14, 9065-9072. | 0.9 | 13 |
| 7 | Non-Invasive Plasma Monitoring Tools and Multivariate Analysis Techniques for Sensitivity Improvement. Applied Science and Convergence Technology, 2014, 23, 328-339. | 0.9 | 4 |
| 8 | Real-Time Endpoint Detection of Small Exposed Area SiO ₂ Films in Plasma Etching Using Plasma Impedance Monitoring with Modified Principal Component Analysis. Plasma Processes and Polymers, 2013, 10, 850-856. | 3.0 | 10 |
| 9 | Characterization of Low-k Dielectric SiCOH Films Deposited with Decamethylcyclopentasiloxane and Cyclobexane, Journal of Nanoscience and Nanotechnology, 2012, 12, 6040-6044. | 0.9 | 2 |